

# Product Manual

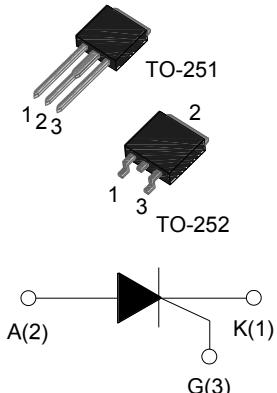
EKWIN ELECTRONICS CO.,LTD

**EK TN615**

[www.ekwin.net](http://www.ekwin.net)


**6A SCRs**
**TN615 Serial**
**Main Features:**

<b>IT(RMS)</b>	<b>VDRM/VRRM</b>	<b>VTM</b>
6 A	600V and 800 V	$\leq 1.6$ V

**Description:**


The TN615 family of Silicon Controlled Rectifiers are high performance Glass passivated, sensitive gate thyristors in a plastic envelope, intended for use in general purpose switching and phase control applications. These devices are intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

**Absolute Ratings(limiting values) :**

<b>Symbol</b>	<b>Parameter</b>		<b>value</b>	<b>Unit</b>
<b>I<sub>T(RMS)</sub></b>	on-state RMS current(180°C conduction angle)		6	A
<b>I<sub>TSM</sub></b>	Non repetitive surge peak on-state current (T <sub>j</sub> = 25 °C)	tp= 8.3 ms	73	A
		tp = 10 ms	70	
<b>V<sub>DRM</sub></b>	Repetitive peak off-state voltage(T <sub>j</sub> =25°C)		600 and 800	V
<b>V<sub>RPM</sub></b>	Repetitive peak reverse voltage(T <sub>j</sub> =25°C)		600 and 800	V
<b>T<sub>stg</sub> T<sub>j</sub></b>	Storage and operating junction temperature range		- 40 to + 150 - 40 to + 125	°C
<b>I<sup>2</sup>t</b>	I <sup>2</sup> t value for fusing T <sub>j</sub> = 125°C	tp = 10 ms	25	A <sup>2</sup> s
<b>dI/dt</b>	Critical rate of rise of on-state current I <sub>G</sub> =2xI <sub>GT</sub> , tr≤100ns		50	A/μs

### Electrical Characteristics :

<b>Symbol</b>	<b>Test Condition</b>		<b>range</b>	<b>Value</b>	<b>Unit</b>
<b>I<sub>GT</sub></b>	V <sub>D</sub> =12V      R <sub>L</sub> =3.3kΩ	T <sub>j</sub> =25°C	MAX	15	mA
<b>V<sub>GT</sub></b>		T <sub>j</sub> =25°C	MAX	1.5	V
<b>V<sub>GD</sub></b>	V <sub>D</sub> =V <sub>DRM</sub> R <sub>L</sub> =3.3kΩ	T <sub>j</sub> =125°C	MIN	0.2	V
<b>t<sub>gt</sub></b>	V <sub>D</sub> =V <sub>DRM</sub> I <sub>G</sub> = 500mA    dI <sub>G</sub> /dt = 0.2A/μs	T <sub>j</sub> =25°C	TYP	2	μs
<b>I<sub>L</sub></b>	V <sub>D</sub> =12V    I <sub>GT</sub> = 0.1 A	T <sub>j</sub> =25°C	TYP	50	mA
<b>I<sub>H</sub></b>	I <sub>T</sub> = 500mA gate open	T <sub>j</sub> =25°C	MAX	30	mA
<b>V<sub>TM</sub></b>	I <sub>TM</sub> = 2*I <sub>T</sub> (RMS)    tp=380μs	T <sub>j</sub> =25°C	MAX	1.6	V
<b>I<sub>DRM</sub></b> <b>I<sub>RRM</sub></b>	V <sub>D</sub> =V <sub>DRM</sub> , V <sub>R</sub> =V <sub>RRM</sub>	T <sub>j</sub> =125°C	TYP	10	μA
		T <sub>j</sub> =125°C	MAX	2	mA
<b>dV<sub>D</sub>/dt</b>	V <sub>D</sub> =67%V <sub>DR</sub> exponential waveform; R <sub>GK</sub> = 100 Ω	T <sub>j</sub> =125°C	TYP	200	V/μs

### Thermal Resistances :

<b>Symbol</b>	<b>Parameter</b>		<b>Value</b>	<b>Unit</b>
<b>R<sub>th</sub> (j-c)</b>	junction to mounting base	TO-251/252	2.5	°C/W
<b>R<sub>th</sub> (j-a)</b>	Junction to ambient	TO-251/252	60	°C/W

Fig.1: Maximum average power dissipation versus average on-state current .

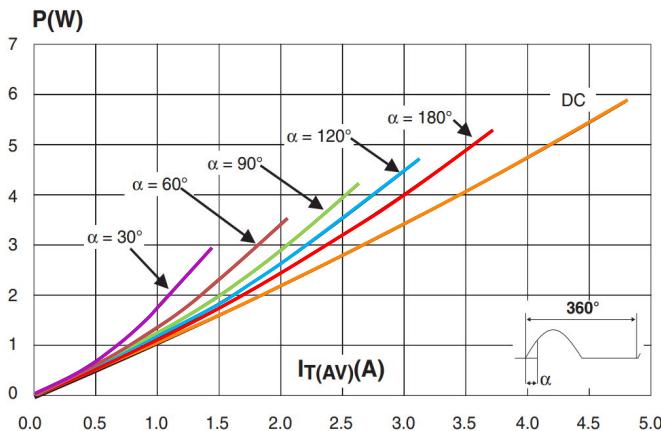


Fig.3 : Average and D.C. on-state current versus case temperature.

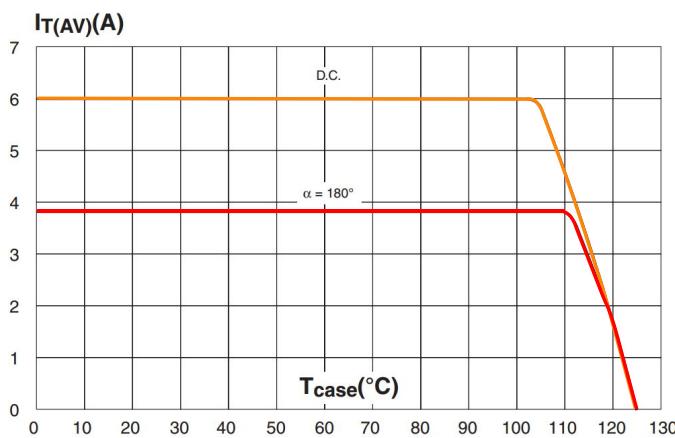


Fig.5 : Relative variation of thermal impedance versus pulse duration.

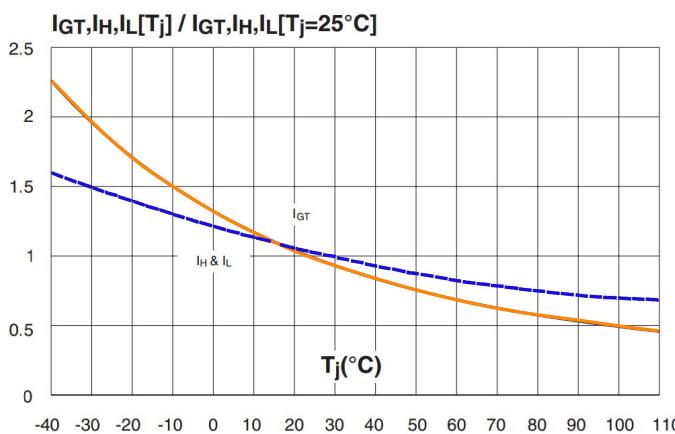


Fig.2 : Correlation between maximum average power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{case}$ ) for different thermal resistances heat sink+contact.

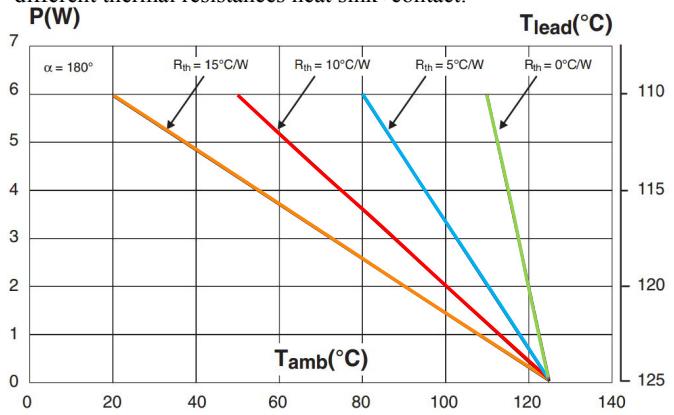


Fig.4 : Average and D.C. on-state current versus case temperature.

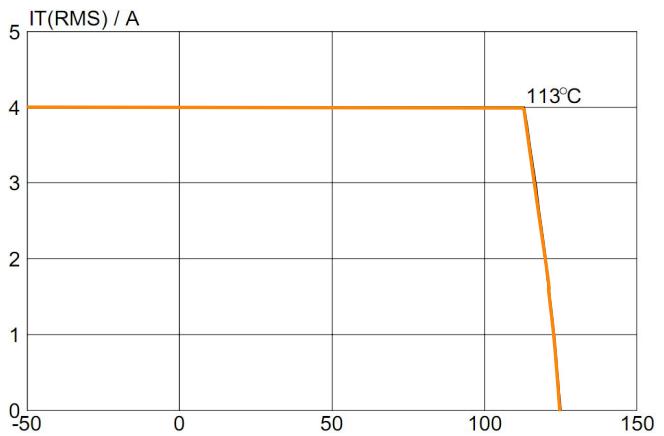


Fig.6 : Relative variation of thermal impedance versus pulse duration.

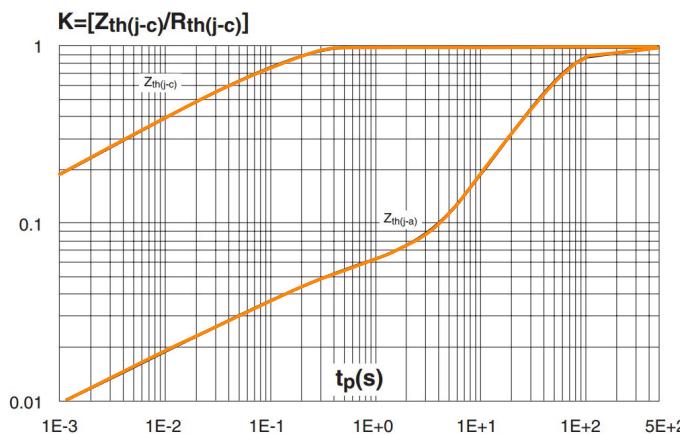


Fig.7 : Relative variation of gate trigger current and holding current versus junction temperature.

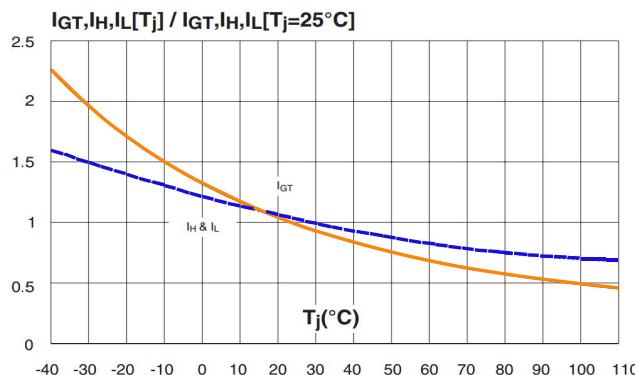
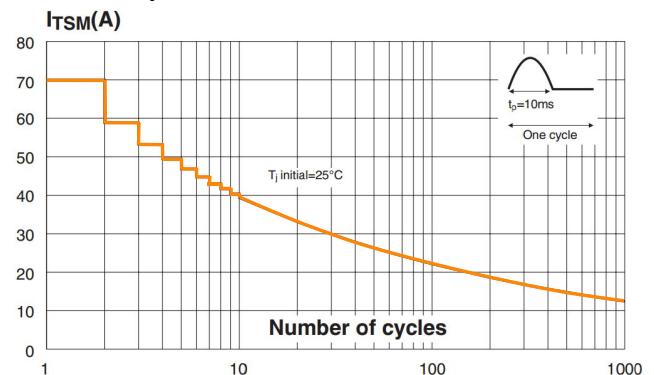
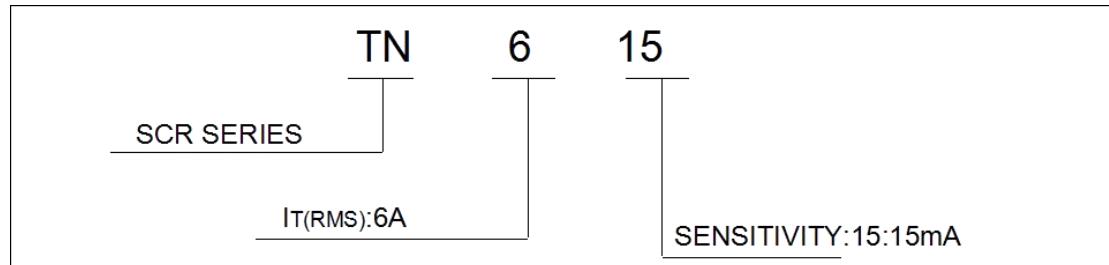


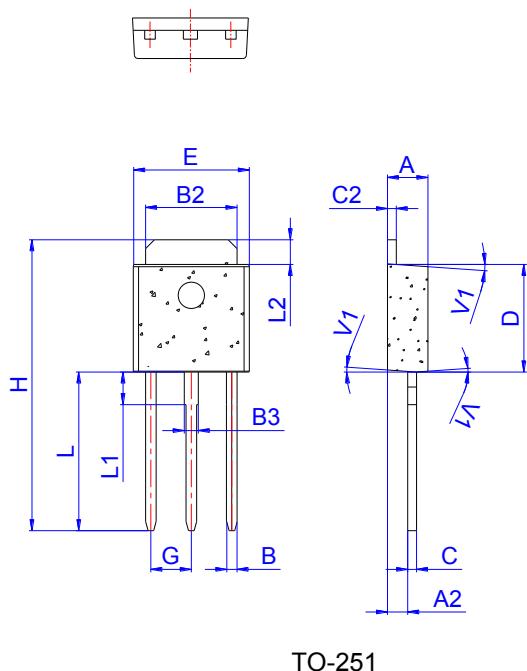
Fig.6: Non repetitive surge peak on-state current versus number of cycles.



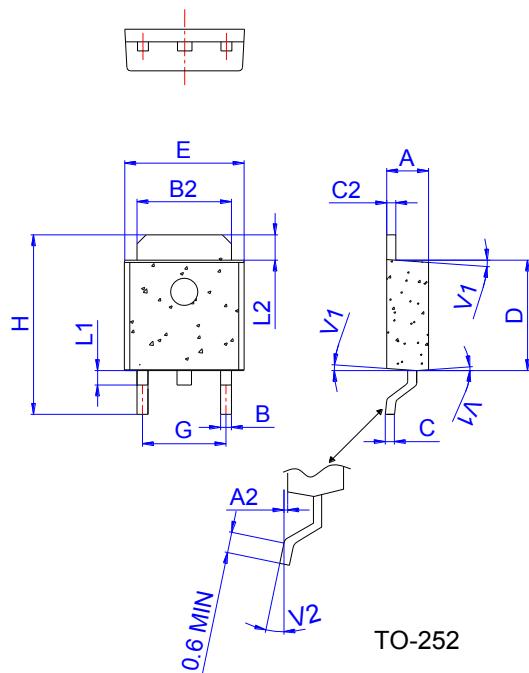
## Ordering Information



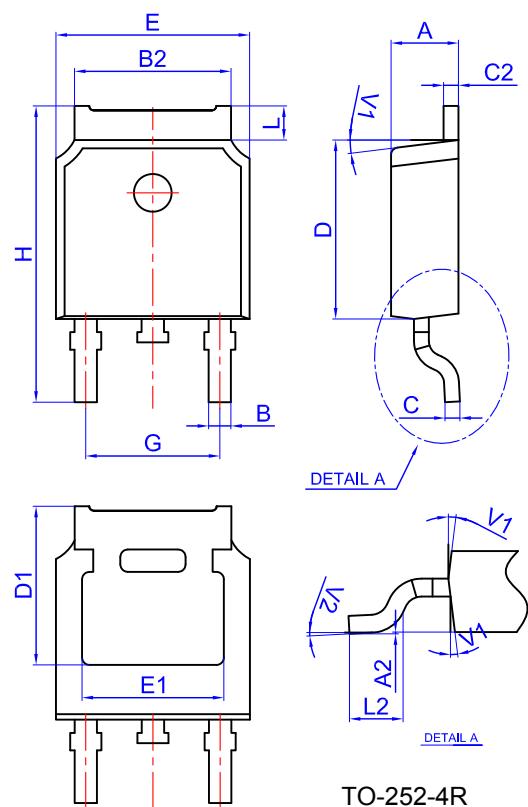
## Package Mechanical Data :



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.20		2.40	0.086		0.095
A2	0.90		1.20	0.035		0.047
B	0.55		0.65	0.022		0.026
B2	5.10		5.40	0.200		0.213
B3	0.76		0.85	0.030		0.033
C	0.45		0.62	0.018		0.024
C2	0.48		0.62	0.019		0.024
D	6.00		6.20	0.236		0.244
E	6.40		6.70	0.252		0.264
G		2.30			0.091	
H	16.0		17.0	0.630		0.669
L	8.90		9.40	0.350		0.370
L1	1.80		1.90	0.071		0.075
L2	1.37		1.50	0.054		0.059
V1		4°			4°	



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.20		2.40	0.086		0.095
A2	0.03		0.23	0.001		0.009
B	0.55		0.65	0.022		0.026
B2	5.10		5.40	0.200		0.213
C	0.45		0.62	0.018		0.024
C2	0.48		0.62	0.019		0.024
D	6.00		6.20	0.236		0.244
E	6.40		6.70	0.252		0.264
G	4.40		4.70	0.173		0.185
H	9.35		10.6	0.368		0.417
L1	1.30		1.70	0.051		0.067
L2	1.37		1.50	0.054		0.059
V1		4°			4°	
V2	0°		8°	0°		8°



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°